

GaAs INTEGRATED CIRCUIT $\mu PG2160T5K$

L, S-BAND SPDT SWITCH

DESCRIPTION

The μ PG2160T5K is a GaAs MMIC for L, S-band SPDT (<u>Single Pole Double Throw</u>) switch which was developed for mobile phone and another L, S-band applications.

This device can operate frequency from 0.5 to 3.0 GHz, having the low insertion loss and high isolation.

This device is housed in a 6-pin plastic TSSON (<u>Thin Shrink Small Out-line Non-leaded</u>) package. And this package is able to high-density surface mounting.

FEATURES

•	Supply voltage	: VDD = 2.4 to 2.8 V (2.6 V TYP.)
•	Switch control voltage	: V _{cont (H)} = 2.4 to V _{DD} (2.6 V TYP.)
		: $V_{\text{cont (L)}} = -0.2 \text{ to } 0.2 \text{ V} (0 \text{ V TYP.})$
•	Low insertion loss	: Lins1 = 0.30 dB TYP. @ f = 0.5 to 1.0 GHz, VDD = 2.6 V, Vcont (H) = 2.6 V, Vcont (L) = 0 V
		: Lins2 = 0.35 dB TYP. @ f = 1.0 to 2.0 GHz, VDD = 2.6 V, Vcont (H) = 2.6 V, Vcont (L) = 0 V
		: Lins3 = 0.40 dB TYP. @ f = 2.0 to 2.5 GHz, VDD = 2.6 V, Vcont (H) = 2.6 V, Vcont (L) = 0 V
		: Lins4 = 0.50 dB TYP. @ f = 2.5 to 3.0 GHz, V_{DD} = 2.6 V, $V_{cont (H)}$ = 2.6 V, $V_{cont (L)}$ = 0 V
•	High isolation	: ISL1 = 25 dB TYP. @ f = 0.5 to 1.0 GHz, V_{DD} = 2.6 V, $V_{cont (H)}$ = 2.6 V, $V_{cont (L)}$ = 0 V
		: ISL2 = 18 dB TYP. @ f = 1.0 to 2.0 GHz, V_{DD} = 2.6 V, $V_{cont (H)}$ = 2.6 V, $V_{cont (L)}$ = 0 V
		: ISL3 = 17 dB TYP. @ f = 2.0 to 2.5 GHz, V_{DD} = 2.6 V, $V_{cont (H)}$ = 2.6 V, $V_{cont (L)}$ = 0 V
		: ISL4 = 13 dB TYP. @ f = 2.5 to 3.0 GHz, V_{DD} = 2.6 V, $V_{cont (H)}$ = 2.6 V, $V_{cont (L)}$ = 0 V
•	Handling power	: Pin (0.1 dB) = +21.0 dBm TYP. @ f = 2.0/2.5 GHz, VDD = 2.6 V, Vcont (H) = 2.6 V, Vcont (L) = 0 V
	Lligh density surface may nation	μ 6 min plastic TECON package (1.0 \times 1.0 \times 0.07 mm)

• High-density surface mounting : 6-pin plastic TSSON package $(1.0 \times 1.0 \times 0.37 \text{ mm})$

APPLICATIONS

- L, S-band digital cellular or cordless telephone
- W-LAN, WLL and Bluetooth[™] etc.

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPG2160T5K-E2	μPG2160T5K-E2-A	6-pin plastic TSSON (Pb-Free) ^{№te}	G4	Embossed tape 8 mm widePin 1, 6 face the perforation side of the tapeQty 5 kpcs/reel

Note With regards to terminal solder (the solder contains lead) plated products (conventionally plated), contact your nearby sales office.

Remark To order evaluation samples, contact your nearby sales office. Part number for sample order: μ PG2160T5K

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	OUTPUT1
2	GND
3	OUTPUT2
4	Vcont
5	INPUT
6	VDD

TRUTH TABLE

Vcont	INPUT-OUTPUT1	INPUT-OUTPUT2
High	OFF	ON
Low	ON	OFF

ABSOLUTE MAXIMUM RATINGS (TA = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	VDD	+6.0	V
Switch Control Voltage	Vcont	+6.0	V
Input Power	Pin	+26	dBm
Operating Ambient Temperature	TA	–45 to +85	°C
Storage Temperature	Tstg	-55 to +135	°C

RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage Note	VDD	2.4	2.6	2.8	V
Switch Control Voltage (H) Note	Vcont (H)	2.4	2.6	VDD	V
Switch Control Voltage (L)	Vcont (L)	-0.2	0	0.2	V

Note $V_{\text{cont}(H)} \leq V_{\text{DD}}$

ELECTRICAL CHARACTERISTICS

(TA = +25°C, V_{DD} = 2.6 V, V_{cont (H)} = 2.6 V, V_{cont (L)} = 0 V, DC cut capacitors = 56 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	Lins1	f = 0.5 to 1.0 GHz	-	0.30	0.45	dB
Insertion Loss 2	Lins2	f = 1.0 to 2.0 GHz	-	0.35	0.50	
Insertion Loss 3	Lins3	f = 2.0 to 2.5 GHz	-	0.40	0.55	
Insertion Loss 4	Lins4	f = 2.5 to 3.0 GHz	_	0.50	0.65	
Isolation 1	ISL1	f = 0.5 to 1.0 GHz	22	25	-	dB
Isolation 2	ISL2	f = 1.0 to 2.0 GHz	15	18	_	
Isolation 3	ISL3	f = 2.0 to 2.5 GHz	14	17	-	
Isolation 4	ISL4	f = 2.5 to 3.0 GHz	10	13	_	
Input Return Loss	RLin	f = 0.5 to 3.0 GHz	15	20	-	dB
Output Return Loss	RLout	f = 0.5 to 3.0 GHz	15	20	-	dB
0.1 dB Loss Compression Input Power Note	Pin (0.1 dB)	f = 2.0/2.5 GHz	+18.0	+21.0	-	dBm
2nd Harmonics	2fo	f = 2.0/2.5 GHz, P _{in} = +10 dBm	65	75	-	dBc
3rd Harmonics	3f o	f = 2.0/2.5 GHz, P _{in} = +10 dBm	65	75	-	dBc
Supply Current	ldd	No signal	-	50	100	μA
Switch Control Current	Icont		-	4	20	μA
Switch Control Speed	tsw	50% CTL to 90/10% RF	-	150	-	ns

Note Pin (0.1 dB) is measured the input power level when the insertion loss increases more 0.1 dB than that of linear range.

Caution This device is used it is necessary to use DC cut capacitors.

EVALUATION CIRCUIT





The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.



ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

USING THE NEC EVALUATION BOARD

Symbol	Values
C1, C2, C3	56 pF
C4, C5	1 000 pF



Remark The graphs indicate nominal characteristics.

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OUTPUT POWER vs. INPUT POWER



Remark The graphs indicate nominal characteristics.

MOUNTING PAD DIMENSIONS

6-PIN PLASTIC TSSON (UNIT: mm)



Remark The mounting pad layouts in this document are for reference only.

PACKAGE DIMENSIONS

6-PIN PLASTIC TSSON (UNIT: mm)

(Top View)







RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.
	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	 Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
	2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	• Do not lick the product or in any way allow it to enter the mouth.

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